



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-06-29
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacobello	Representative Title	IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	MQYG*UI56AB5	A	Z6HA	2015-06-29
Amount	UoM	Unit type	ST ECOPACK Grade	
24.40	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	3X3X0.95	6	No lead	
Comment	Package: VFDFPN 6 3X3 0,95 PITCH; MDF valid for LD39200PU33R			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MQYG*UI56A5						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Silicon die	Other inorganic materials	1.599	mg	supplier	die	Silicon (Si)	7440-21-3		1.496	mg	935585	61311	
Silicon die				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	11257	738	
Silicon die				supplier	metallization	Tungsten (W)	7440-33-7		0.015	mg	9381	615	
Silicon die				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.004	mg	2502	164	
Silicon die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.031	mg	19387	1270	
Silicon die				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	625	41	
Silicon die				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	2502	164	
Silicon die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.01	mg	6254	410	
Silicon die				supplier	back side metallization	Vanadium (V)	7440-62-2		0.001	mg	625	41	
Silicon die				supplier	polymer die coating	PIXI Gamma-butyrolactone	96-48-0		0.019	mg	11882	779	
Leadframe	Copper & its alloys	8.514	mg	supplier	alloy	Copper (Cu)	7440-50-8		8.223	mg	965821	337008	
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.192	mg	22551	7869	
Leadframe				supplier	alloy	Lead (Pb)	7439-92-1		0.001	mg	117	41	
Leadframe				supplier	alloy	Phosphorus (P)	12185-10-3		0.002	mg	235	82	
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.01	mg	1175	410	
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.086	mg	10101	3525	
Die attach	Other organic materials	0.089	mg	supplier	glue	Silver (Ag)	7440-22-4		0.073	mg	820225	2992	
Die attach				supplier	glue	Carbocyclic Acrylates	proprietary		0.009	mg	101124	369	
Die attach				supplier	glue	Bismaleimide resin	35325-39-4		0.003	mg	33708	123	
Die attach				supplier	glue	2-preponoic acid, 2-methyl	68586-19-6		0.003	mg	33708	123	
Die attach				supplier	glue	Dicumyl peroxide	80-43-3		0.001	mg	11236	41	
Bonding wire	Other organic materials	0.083	mg	supplier	wire	Copper (Cu)	7440-50-8		0.083	mg	1000000	3402	
encapsulation	Other organic materials	13.918	mg	supplier	mold compound	Silica Fused	60676-86-0		13.042	mg	937060	534508	
encapsulation				supplier	mold compound	Epoxy Resin	25068-38-6		0.417	mg	29961	17090	
encapsulation				supplier	mold compound	Phenol Resin	29690-82-2		0.418	mg	30033	17131	
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		0.041	mg	2946	1680	
connections coating	Solder	0.197	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.197	mg	1000000	8074	